



flowPACK 1

1200 V / 50 A

Topology features

- Inverter
- Kelvin Emitter for improved switching performance
- Temperature sensor

Component features

- Easy paralleling
- Low turn-off losses
- Low collector emitter saturation voltage
- Positive temperature coefficient
- Short tail current
- Switching optimized for EMC

Housing features

- Base isolation: AlN
- Convex shaped substrate for superior thermal contact
- Thermo-mechanical push-and-pull force relief
- Solder pin

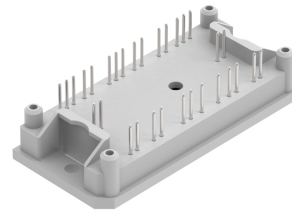
Target applications

- Heat Pumps
- Industrial Drives
- Servo Drives

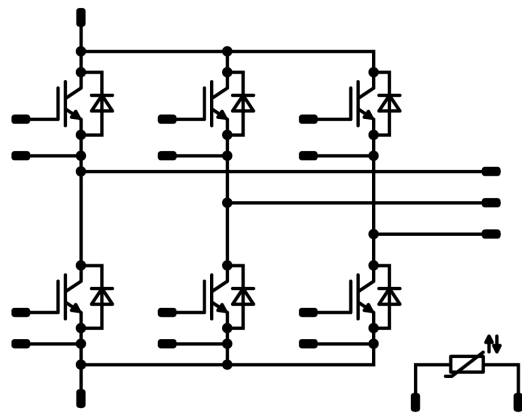
Types

- 10-F1126PA050M701-L828F19

flow 1 17 mm housing



Schematic





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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	75	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	100	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	180	W
Gate-emitter voltage	V_{GES}		± 20	V
Short circuit ratings	i_{SC}	$V_{GE} = 15\text{ V}$, $V_{CC} = 800\text{ V}$ $T_j = 150\text{ °C}$	9,5	μs
Maximum junction temperature	T_{jmax}		175	$^{\circ}\text{C}$

Inverter Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	65	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	100	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	131	W
Maximum junction temperature	T_{jmax}		175	$^{\circ}\text{C}$

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	$^{\circ}\text{C}$
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	$^{\circ}\text{C}$

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Creepage distance			>12,7	mm
Clearance			12,64	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	

Inverter Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,005	25	5,4	6	6,6	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		50	25 125 150		1,55 1,77 1,83	1,9 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			0,09	mA
Gate-emitter leakage current	I_{GES}		20	0		25			0,5	μA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}							10000		pF
Output capacitance	C_{oes}		0	10		25		350		pF
Reverse transfer capacitance	C_{res}							130		pF
Gate charge	Q_g	$V_{CC} = 600$ V	0/15		50	25		380		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{foil}=220$ W/mK (KU-ALF5)						0,53		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$					25 125 150		169,76 168,04 166,95		ns
Rise time	t_r	$R_{gon} = 8 \Omega$ $R_{goff} = 8 \Omega$				25 125 150		34,03 37,3 38,48		ns
Turn-off delay time	$t_{d(off)}$		±15	600	50	25 125 150		187,98 216,32 223,51		ns
Fall time	t_f					25 125 150		101,29 134,79 144,9		ns
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD}=4,43 \mu C$ $Q_{tFWD}=6,96 \mu C$ $Q_{tFWD}=7,91 \mu C$				25 125 150		3,77 4,77 5,06		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		3,71 5,12 5,51		mWs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		
Inverter Diode										
Static										
Forward voltage	V_F			50	25 125 150		1,66 1,78 1,79	2,1 ⁽¹⁾		V
Reverse leakage current	I_R	$V_r = 1200$ V			25			40		μA
Thermal										
Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{foil}=220$ W/mK (KU-ALF5)					0,72			K/W
Dynamic										
Peak recovery current	I_{RM}				25 125 150		39,01 42,56 44,41			A
Reverse recovery time	t_{rr}				25 125 150		276,68 416,97 464,25			ns
Recovered charge	Q_r	$di/dt=1142$ A/μs $di/dt=1224$ A/μs $di/dt=1212$ A/μs	±15	600	50	25 125 150	4,43 6,96 7,91			μC
Reverse recovered energy	E_{rec}				25 125 150		1,76 2,87 3,3			mWs
Peak rate of fall of recovery current	$(di_r/dt)_{max}$				25 125 150		459,2 322,31 297,11			A/μs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit	
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	V_{CE} [V]	V_F [V]	I_D [A]	I_C [A]	I_F [A]		T_j [°C]

Thermistor

Static

Rated resistance	R					25		4,7		kΩ
Deviation of R100	$A_{R/R}$	$R_{100} = 401 \Omega$				100	-12		13,1	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 3 \%$						3612		K
B-value	$B_{(25/100)}$	Tol. $\pm 3 \%$						3650		K
Vincotech Thermistor Reference									U	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

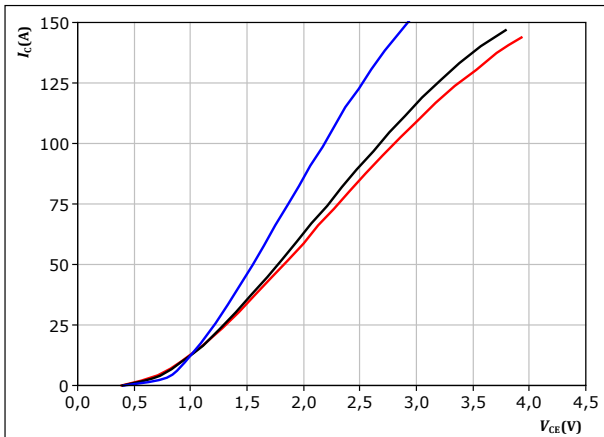


Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



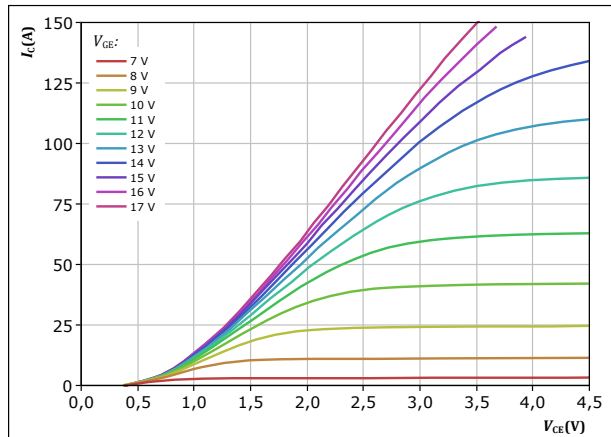
$t_p = 250 \mu s$
 $V_{GE} = 15 V$

$T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



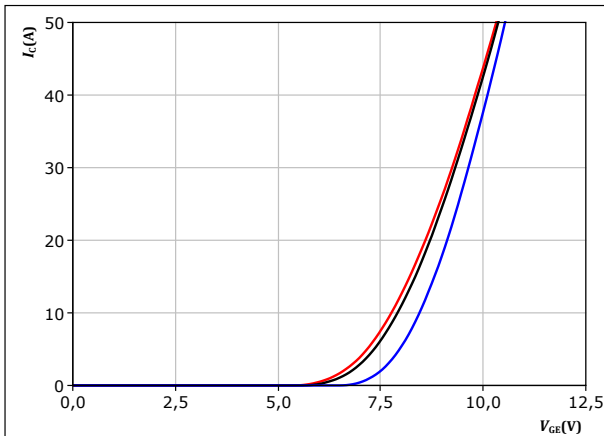
$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ C$

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$



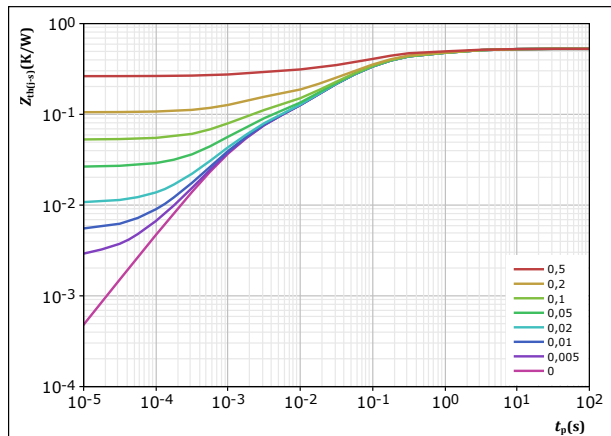
$t_p = 250 \mu s$
 $V_{CE} = 10 V$

$T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,527 \text{ K/W}$

IGBT thermal model values

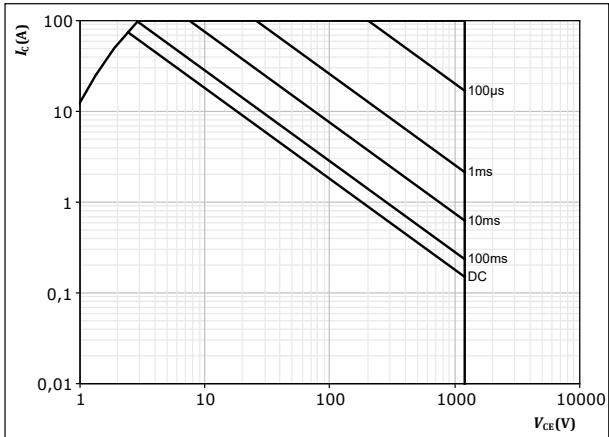
R (K/W)	τ (s)
2,37E-02	5,40E+00
7,94E-02	1,05E+00
2,55E-01	1,00E-01
1,10E-01	2,02E-02
5,85E-02	1,46E-03



Inverter Switch Characteristics

figure 5. IGBT

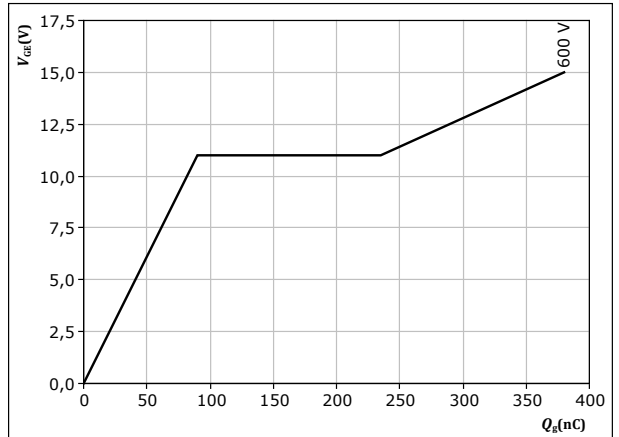
Safe operating area
 $I_C = f(V_{CE})$



$D =$ single pulse
 $T_s = 80$ °C
 $V_{GE} = 15$ V
 $T_j = T_{jmax}$

figure 6. IGBT

Gate voltage vs gate charge
 $V_{GE} = f(Q_g)$



$I_C = 50$ A
 $T_j = 25$ °C



Inverter Diode Characteristics

figure 7. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

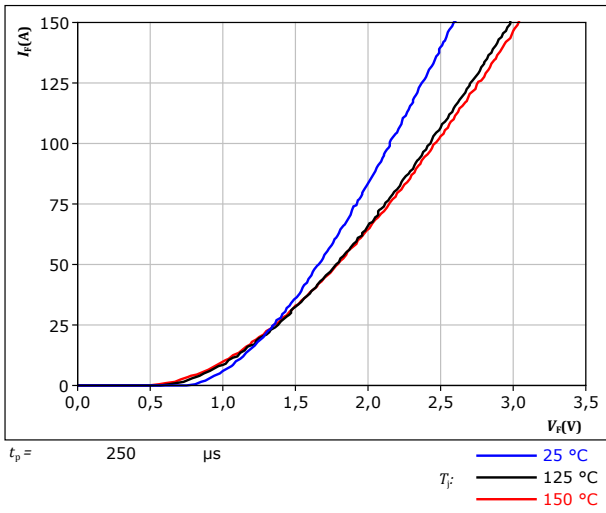
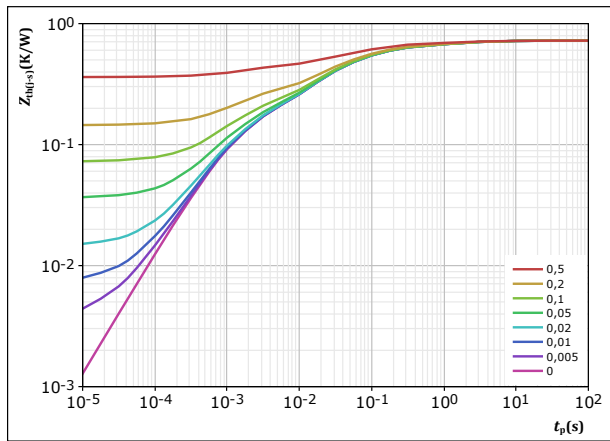


figure 8. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = \frac{t_p}{T}$
 $R_{th(j-s)} = 0,723 \text{ K/W}$
 FWD thermal model values

R (K/W)	τ (s)
2,88E-02	4,88E+00
7,25E-02	8,99E-01
2,22E-01	1,00E-01
2,65E-01	2,02E-02
1,35E-01	1,20E-03

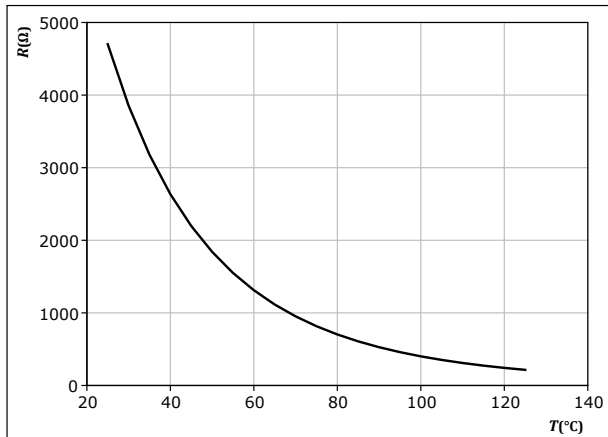


Thermistor Characteristics

figure 9. Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$

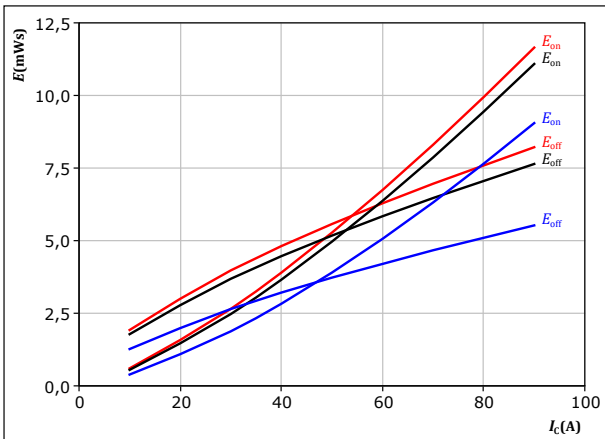




Inverter Switching Characteristics

figure 10. IGBT

Typical switching energy losses as a function of collector current
 $E = f(I_c)$

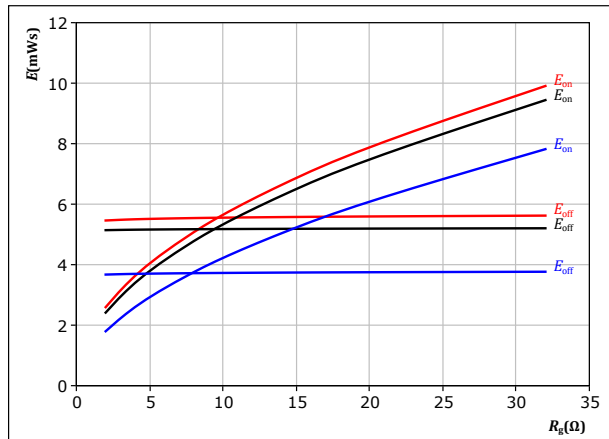


With an inductive load at

$V_{CE} =$	600	V	$T_j:$	25 °C
$V_{GE} =$	±15	V		125 °C
$R_{g(on)} =$	8	Ω		150 °C
$R_{g(off)} =$	8	Ω		

figure 11. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$

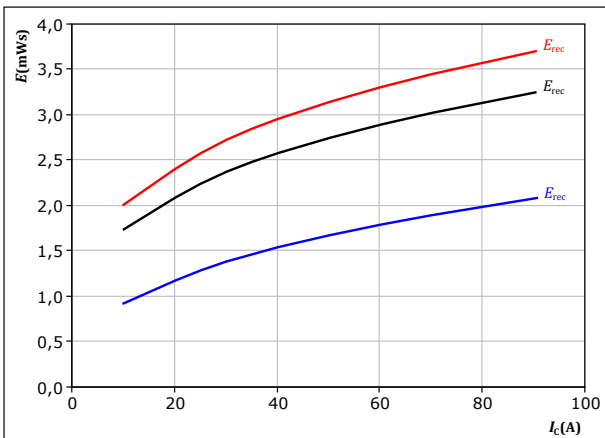


With an inductive load at

$V_{CE} =$	600	V	$T_j:$	25 °C
$V_{GE} =$	±15	V		125 °C
$I_c =$	50	A		150 °C

figure 12. FWD

Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_c)$

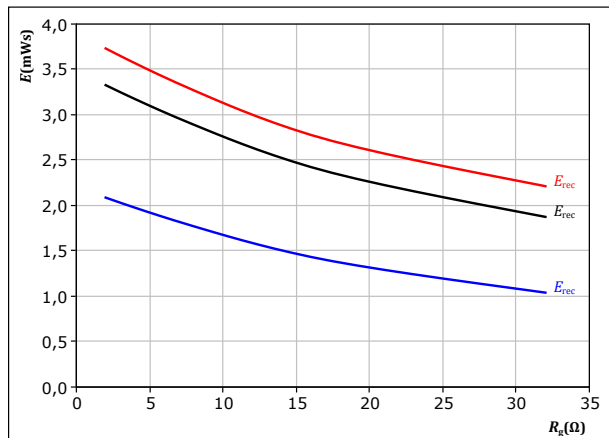


With an inductive load at

$V_{CE} =$	600	V	$T_j:$	25 °C
$V_{GE} =$	±15	V		125 °C
$R_{g(on)} =$	8	Ω		150 °C

figure 13. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



With an inductive load at

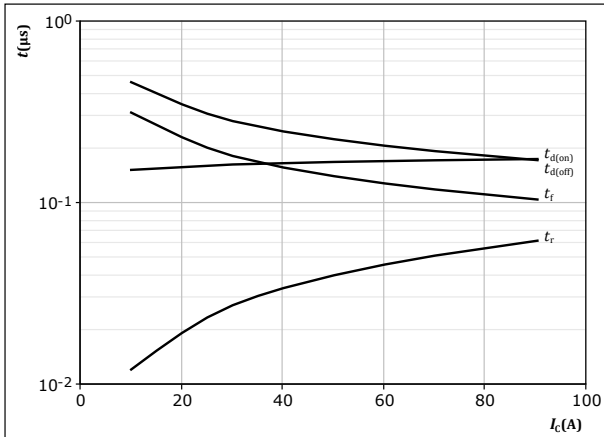
$V_{CE} =$	600	V	$T_j:$	25 °C
$V_{GE} =$	±15	V		125 °C
$I_c =$	50	A		150 °C



Inverter Switching Characteristics

figure 14. IGBT

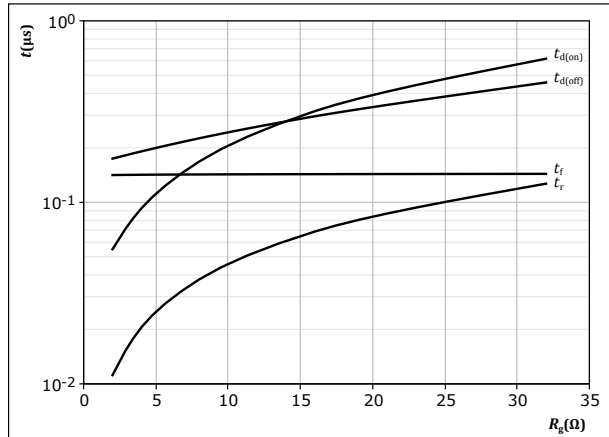
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{g(on)} = 8 \text{ } \Omega$
 $R_{g(off)} = 8 \text{ } \Omega$

figure 15. IGBT

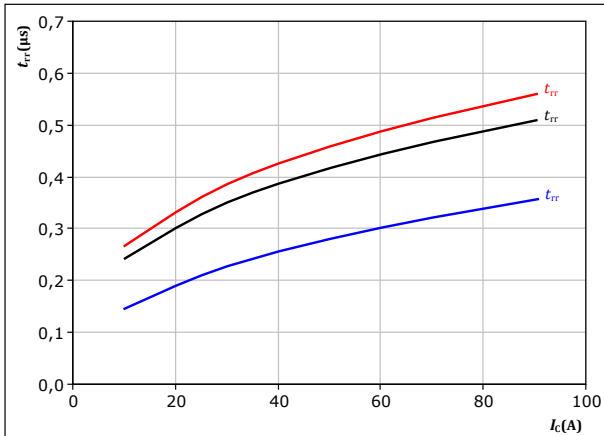
Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 50 \text{ A}$

figure 16. FWD

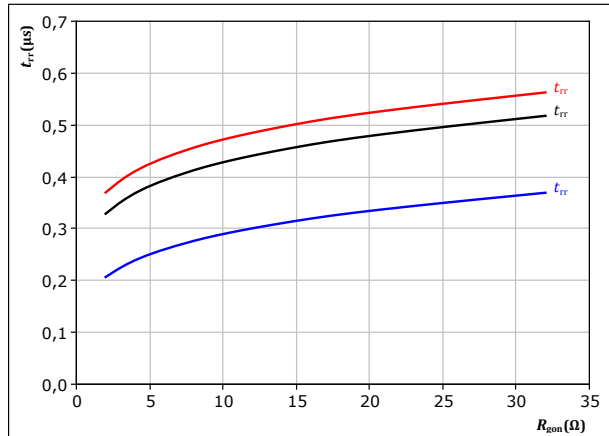
Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{g(on)} = 8 \text{ } \Omega$
 $T_j:$ — 25 $^\circ\text{C}$
 — 125 $^\circ\text{C}$
 — 150 $^\circ\text{C}$

figure 17. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{g(on)})$



With an inductive load at
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 50 \text{ A}$
 $T_j:$ — 25 $^\circ\text{C}$
 — 125 $^\circ\text{C}$
 — 150 $^\circ\text{C}$

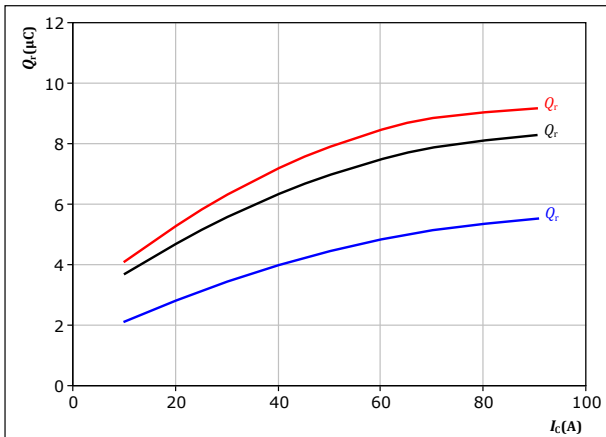


Inverter Switching Characteristics

figure 18. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

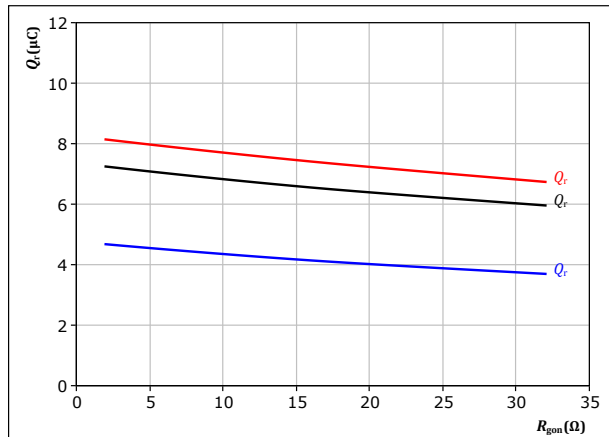
$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \ \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 19. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

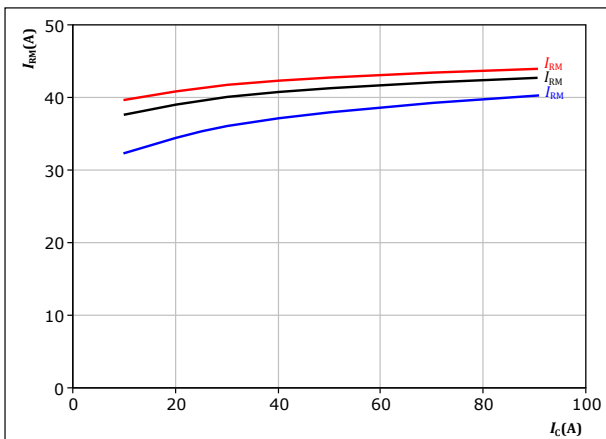
$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 50 \text{ A}$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 20. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

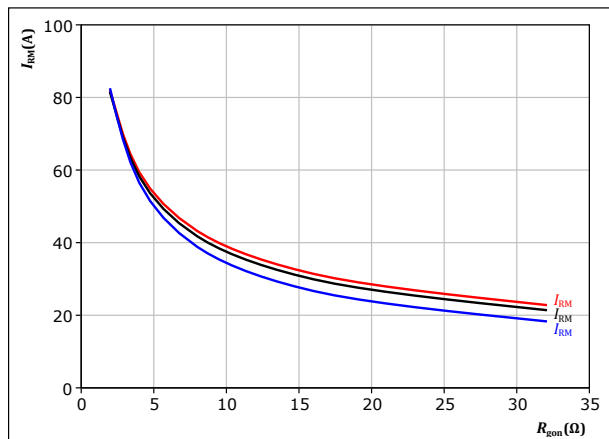
$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \ \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 21. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 50 \text{ A}$

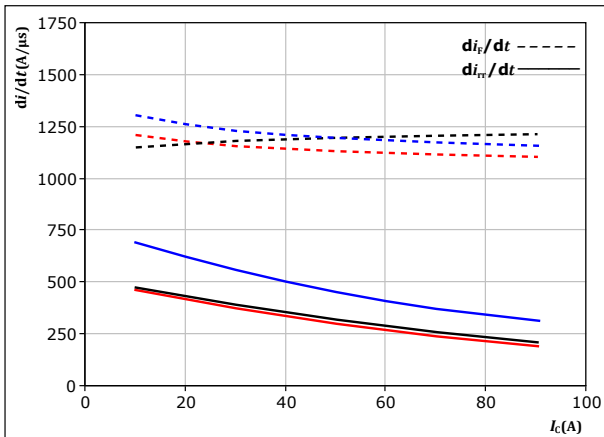
T_j : — 25 °C
— 125 °C
— 150 °C



Inverter Switching Characteristics

figure 22. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_{rr}/dt = f(I_c)$



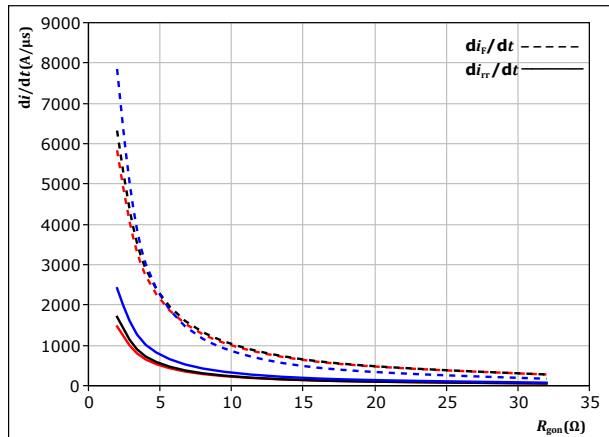
With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \ \Omega$

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 23. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{gon})$



With an inductive load at

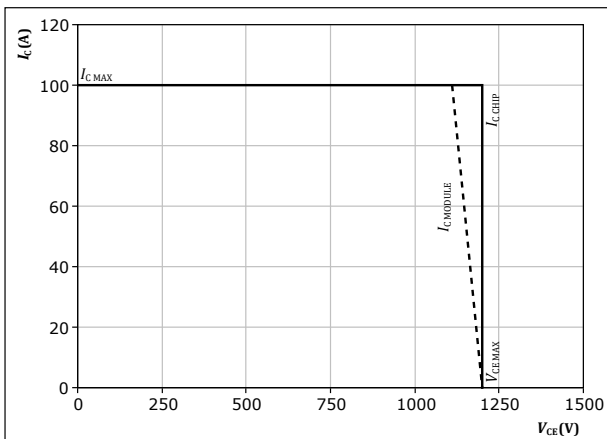
$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 50 \text{ A}$

T_j :
— 25 °C
— 125 °C
— 150 °C

figure 24. IGBT

Reverse bias safe operating area

$I_c = f(V_{CE})$



At $T_j = 150 \text{ °C}$
 $R_{gon} = 8 \ \Omega$
 $R_{goff} = 8 \ \Omega$



Inverter Switching Definitions

figure 25. IGBT
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

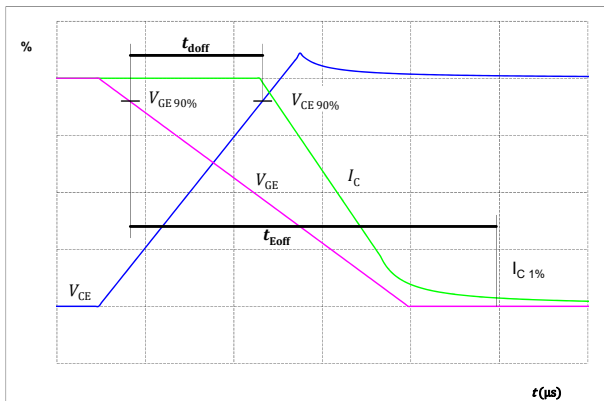


figure 26. IGBT
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})



figure 27. IGBT
Turn-off Switching Waveforms & definition of t_f

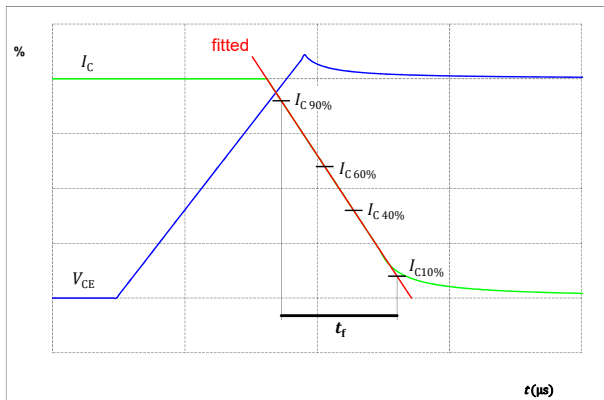
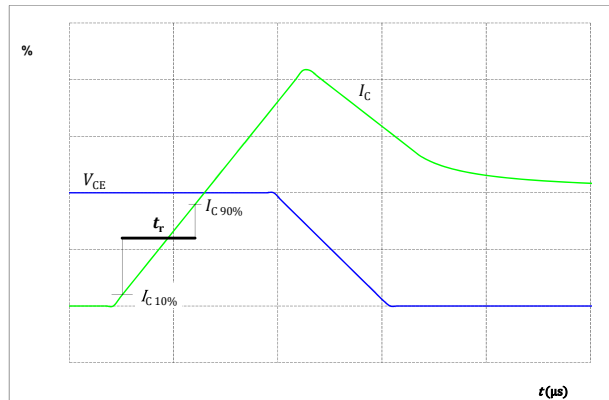


figure 28. IGBT
Turn-on Switching Waveforms & definition of t_r





Inverter Switching Definitions

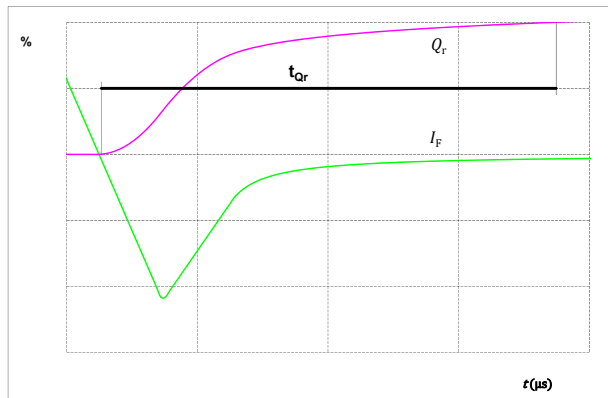
figure 29. FWD

Turn-off Switching Waveforms & definition of t_{rr}



figure 30. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)





Vincotech

10-F1126PA050M701-L828F19
datasheet

Ordering Code	
Version	Ordering Code
Without thermal paste	10-F1126PA050M701-L828F19

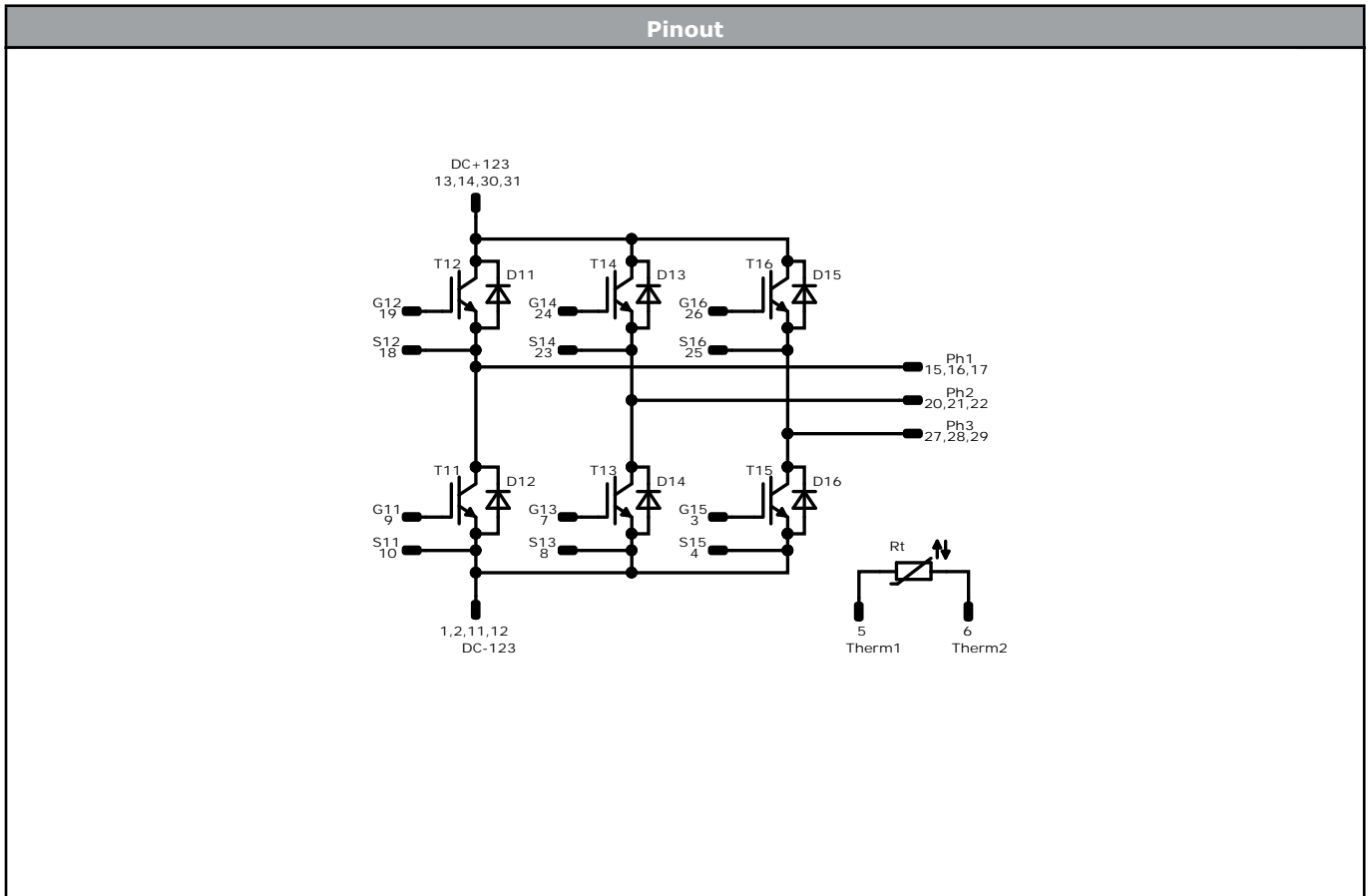
Marking						
	Text	Name	Date code	UL & VIN	Lot	Serial
		NN-NNNNNNNNNNNNNNNN- TTTTIVV	WWYY	UL VIN	LLLLL	SSSS
	Datamatrix	Type&Ver	Lot number	Serial	Date code	
		TTTTIVV	LLLLL	SSSS	WWYY	

Pin table [mm]			
Pin	X	Y	Function
1	52,6	0	DC-
2	49,9	0	DC-
3	42,65	0	G6
4	39,65	0	S6
5	35,15	0	NTC1
6	28,4	0	NTC2
7	24	0	G4
8	21	0	S4
9	12,2	0	G2
10	9,2	0	S2
11	2,7	0	DC-
12	0	0	DC-
13	0	14,65	DC+
14	2,7	14,65	DC+
15	0	28,6	U
16	2,7	28,6	U
17	5,4	28,6	U
18	9,6	28,6	S1
19	12,6	28,6	G1
20	19,6	28,6	V
21	22,3	28,6	V
22	25	28,6	V
23	29,7	28,6	S3
24	32,7	28,6	G3
25	39,7	28,6	S5
26	42,7	28,6	G5
27	47,2	28,6	W
28	49,9	28,6	W
29	52,6	28,6	W
30	52,6	14,65	DC+
31	49,9	14,65	DC+

Tolerance of pinpositions: ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance



Vincotech



Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	50 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	50 A	Inverter Diode	
Rt	Thermistor			Thermistor	



Vincotech

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for <i>flow 1</i> packages see vincotech.com website.

Package data
Package data for <i>flow 1</i> packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}=175^{\circ}\text{C}$ and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website.



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Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.